

A METHOD FOR PRINTING MARKS ON THE EDGES OF WAFERS

Abstract

A method of repeatedly exposing a pattern across a wafer in a sequential stepping process is disclosed. The pattern that is exposed includes at least one alignment mark. Each time the exposing process is repeated, the current exposure overlaps a portion of the wafer where the pattern was previously exposed and thereby erases a previously exposed alignment mark by re-exposing an area of the wafer where the previously exposed alignment mark was located. After the exposing process is repeated across the wafer, alignment marks remain only in the last exposed areas of the wafer.